

## **LISTING OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An integrated active rectifier module comprising;  
a base plate;

a plurality of substrates attached to one surface of said base plate each with a respective flexible adhesive; a heatsink in thermal contact with said base plate and positioned opposite said substrates;

power elements for an active rectifier for supplying recharging power to a battery of an automobile, said active rectifier being mounted on one substrate, and including a plurality of active rectification circuits each connectable to a respective phase of a stator to rectify the power output thereof;

elements for a voltage regulator to regulate the output voltage of said stator, said voltage regulator being mounted on another substrate; and

elements for driving said power elements mounted on another substrate.

2. (Original) An integrated active rectifier module according to claim 1 further comprising, a first lead frame, and a first lead frame support, said lead frame being supported on said first lead frame support over said plurality of substrates.

3. (Original) An integrated active rectifier module according to claim 2, wherein said lead frame support is attached to said base plate.

4. (Original) An integrated active rectifier module according to claim 2, wherein said lead frame support surrounds said plurality of substrate.

5. (Original) An integrated active rectifier module according to claim 1, further comprising a second lead frame, and a second lead frame support, said second lead frame being supported above said first lead frame by said second lead frame support.

6. (Original) An integrated active rectifier module according to claim 5, wherein said first lead frame is used to connect a phase of a stator to said active rectifier and said second lead frame serves as an output lead frame for said active rectifier.

7. Canceled

8. Canceled

9. (Original) An integrated active rectifier module according to claim 1, further comprising a conductive block on at least one of said substrates, said conductive block extending above said substrate.